

INTRODUCING THE IS-G1

INLINE WAFER GRAIN STRUCTURE INSPECTION



**THE PREMIER DEDICATED GRAIN STRUCTURE INSPECTION UNIT FOR
WAFER INSPECTION SORTERS AND SYSTEMS**

MEASUREMENT TECHNIQUE – MULTI-ANGLE OPTICAL REFLECTANCE

ALL WAFER TYPES

FULL WIS LINE SPEED – UP TO 4800 WPH

EASY TO USE GRAPHICAL USER INTERFACE REPORTS

- **GRAIN STRUCTURE MAP**
- **GRAIN BOUNDARY MAP**
- **GRAIN BOUNDARY LENGTH**
- **GRAIN AREA HISTOGRAMS**
- **LARGEST GRAIN AREA AND POSITION**
- **OTHER MEASUREMENTS CAN BE REPORTED BY CUSTOMER REQUEST**

THE IS-G1 INTEGRATES WITH

- **ANY WIS SYSTEM**
- **THE BT IMAGING QS-W2 WIS SYSTEM**
- **CAN BE INTEGRATED WITH BT IMAGING'S PROPRIETARY ILS-W2 PHOTOLUMINESCENCE INSPECTION UNIT TO REPORT DEFECTS IN DIFFERENT GRAIN STRUCTURES**

USE CASES

- **QA & QC ON WAFER PRODUCTION**
- **PROCESS AND PRODUCT DEVELOPMENT FOR BLOCK, WAFER AND CELL LINES**
- **ROOT CAUSE ANALYSIS AND DEBUG ON BLOCK, WAFER AND CELL LINES**
- **HP MULTICRYSTALLINE WAFER PROCESS AND PRODUCT DEVELOPMENT**
- **HP MULTICRYSTALLINE WAFER IDENTIFICATION**
- **SISTER WAFER IDENTIFICATION**